RE01 1500KB Group

CMSIS Driver Package Rev1.00

Introduction

This document explains how to use CMSIS Driver Package for RE01 1500 KB Group and its restrictions. In this package, driver software can be used to shorten development time and increase development efficiency.

Table of Contents

1. CMSIS PACKAGE Introduction

1.1 Folder Structure

Figure 1.1 shows the folder structure of CMSIS Package. It is recommended to read Getting Started folder under Documents folder before you begin the development.

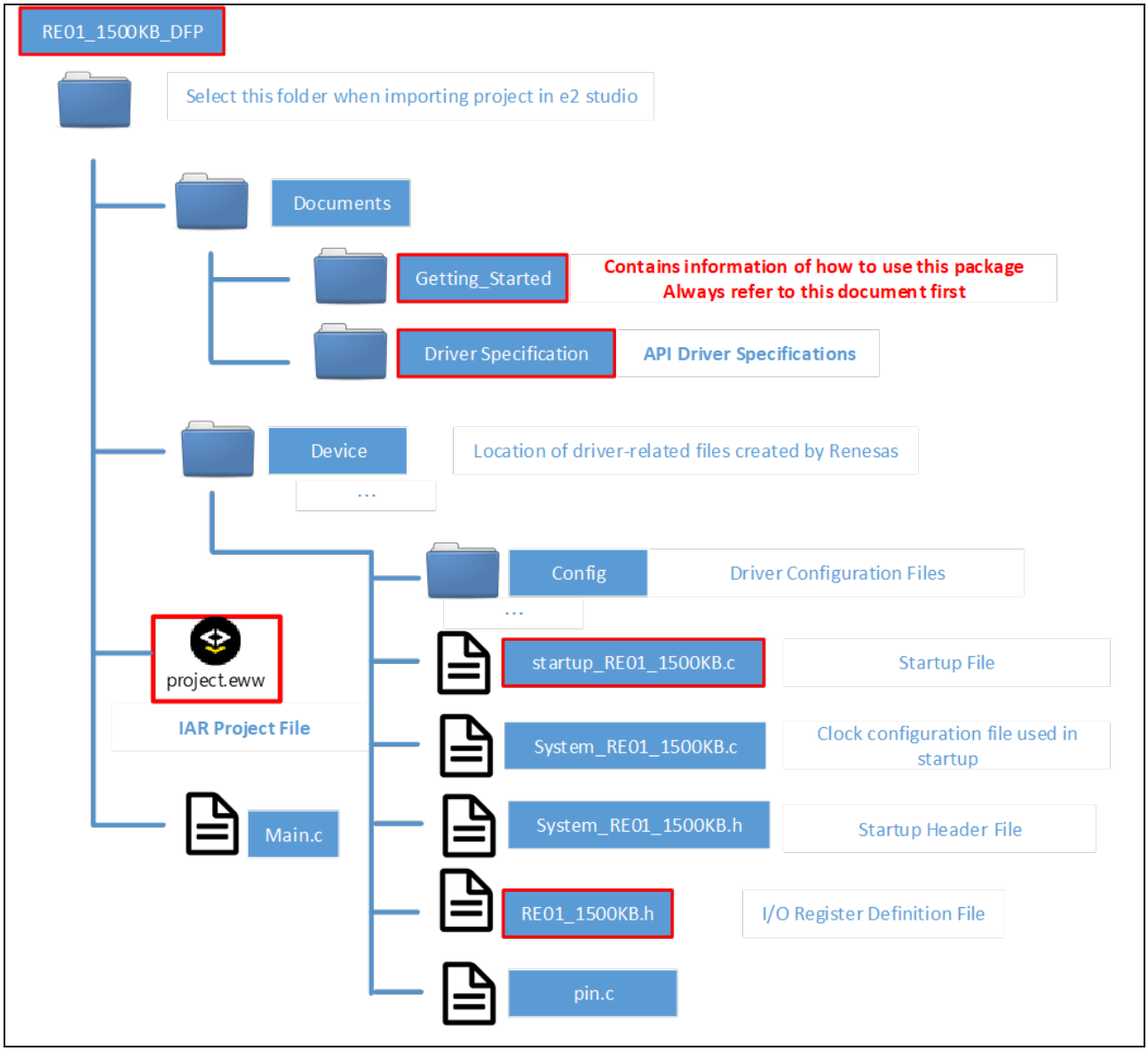

Figure 1.1 Main Files and Folder Structure in CMSIS Package

1.2 Reference Documents

Table 1-1 1.1 Reference Documents

No	Document Name	Content	Document Number
1	Getting Started Guide to Development Using CMSIS Package	Introduction of user code and how to use CMSIS PACKAGE	R01AN4660

2. Operating Environment

2.1 Device

RE Family RE01 1500KB Group

2.2 Development Environment

It is recommended to use CMSIS package with the development environment listed below:

IDE	Compiler	Debugger
IAR EWARM V8.3 or later (IAR Embedded Workbench® for ARM)	IAR v8.32 or Later (Optimize Low)	IAR I-Jet
		Segger J-Link(OB)
Renesas e2 studio V.7 or later	GCC V.6 GNU 6-2017-q2-update (Optimize -O2)	Segger J-Link(OB)

3. Restrictions

3.1 List of Restrictions

1. Restrictions when placing R_GDT driver functions to RAM

   Several API functions do not execute from RAM even though the user sets the correct setting in the configuration file.

2. Restrictions when placing R_PMIP driver functions to RAM

   API function does not execute from RAM even though the user sets the correct setting in the configuration file.

3.2 Details

1. Restrictions when placing R_GDT driver functions to RAM.

   Target Device

   RE01 1500KB Group

   Details

   Even though the user sets all functions to be executed from RAM in r_gdt_cfg.h file, the following 2 functions are not placed in RAM.

```
・static void v_gdt_dmac_blk_upinf_in_array(void) FUNC_LOCATION_PRV_V_GDT_DMAC_BLK_UPINF_IN_ARRAY;
・static e_gdt_err_t e_gdt_judge_cial_dest_mem_size(st_img_out_info_t* st_img_dest_t, uint8_t
 cialgsl) FUNC_LOCATION_PRV_E_GDT_JUDGE_CIAL_DEST_MEM_SIZE;
```

   Countermeasure

   Replace “FUNC_LOCATION_PRV_E_GDT_JUDGE_CIAL_DEST_MEM_SIZE” with “__attribute__ (section (“.ramfunc”)” at the end of each function in r_gdt_api.c file.

```
・static void v_gdt_dmac_blk_upinf_in_array(void)      __attribute__ ((section(".ramfunc")));
・static e_gdt_err_t e_gdt_judge_cial_dest_mem_size(st_img_out_info_t* st_img_dest_t, uint8_t
 cialgsl)      __attribute__ ((section(".ramfunc")));
```

This restriction will be fixed in the next version.

2. Restrictions when placing R_PMIP driver functions to RAM

Target Device

RE01 1500KB Group

Details

Even though the user sets all functions to be executed from RAM in r_pmip_cfg.h file, the following function is not placed in RAM.

```
・static e_pmip_err_t e_mlcd_cpu_normal_trans(uint32_t in_addr, uint32_t out_addr, uint8_t size_h,
 uint16_t size_v, uint32_t line_memsize)FUNC_LOCATION_PRV_E_MLCD_CPU_NORMAL_TRANS;
```

Countermeasure

Replace “FUNC_LOCATION_PRV_E_MLCD_CPU_NORMAL_TRANS” with “__attribute__ (section (“.ramfunc”)” at the end of the function in r_pmip_api.c file.

```
・static e_pmip_err_t e_mlcd_cpu_normal_trans(uint32_t in_addr, uint32_t out_addr, uint8_t size_h,
 uint16_t size_v, uint32_t line_memsize)     __attribute__ ((section(".ramfunc")));
```

This restriction will be fixed in the next version.

3.3 Restriction List History

The symbol “✓” indicates that the restriction applies.

Table 3-1 Restriction List History

Driver Version Rev	1.00
1. Restrictions when placing R_GDT driver functions to RAM	✓
2. Restrictions when placing R_PMIP driver functions to RAM	✓

4. How to Open and Load a Project

4.1 EWARM

When using IAR EWARM, double click .eww file (IAR project file) inside the ZIP file.

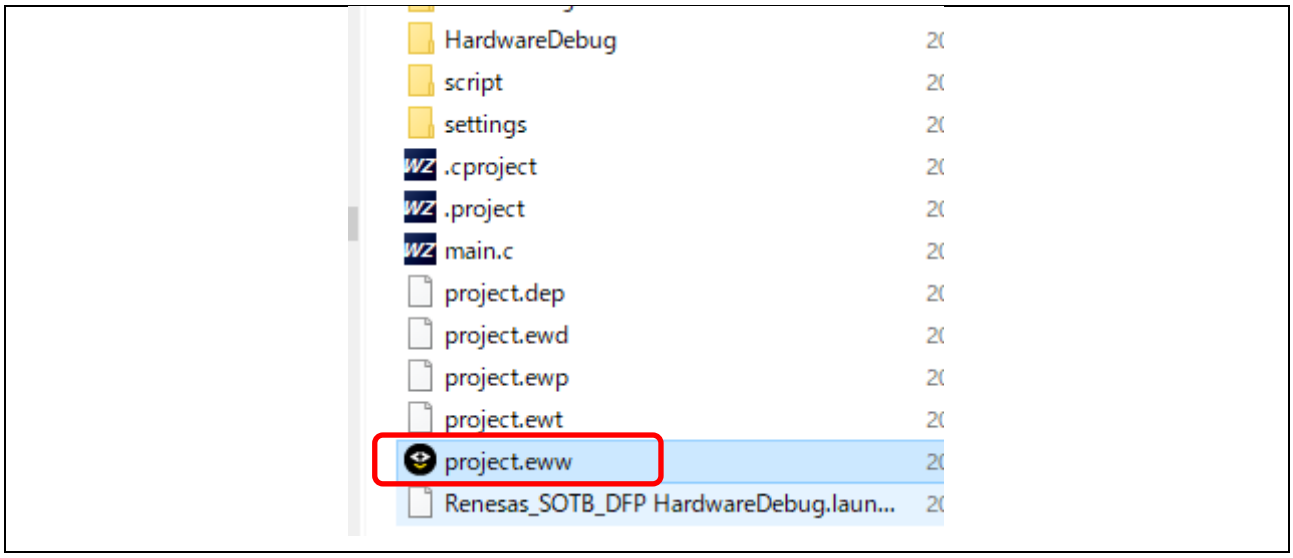

Figure 4.1 How to Open Existing EWARM Project

4.2 e2 studio

When using Renesas e2 studio, follow the steps explained below.

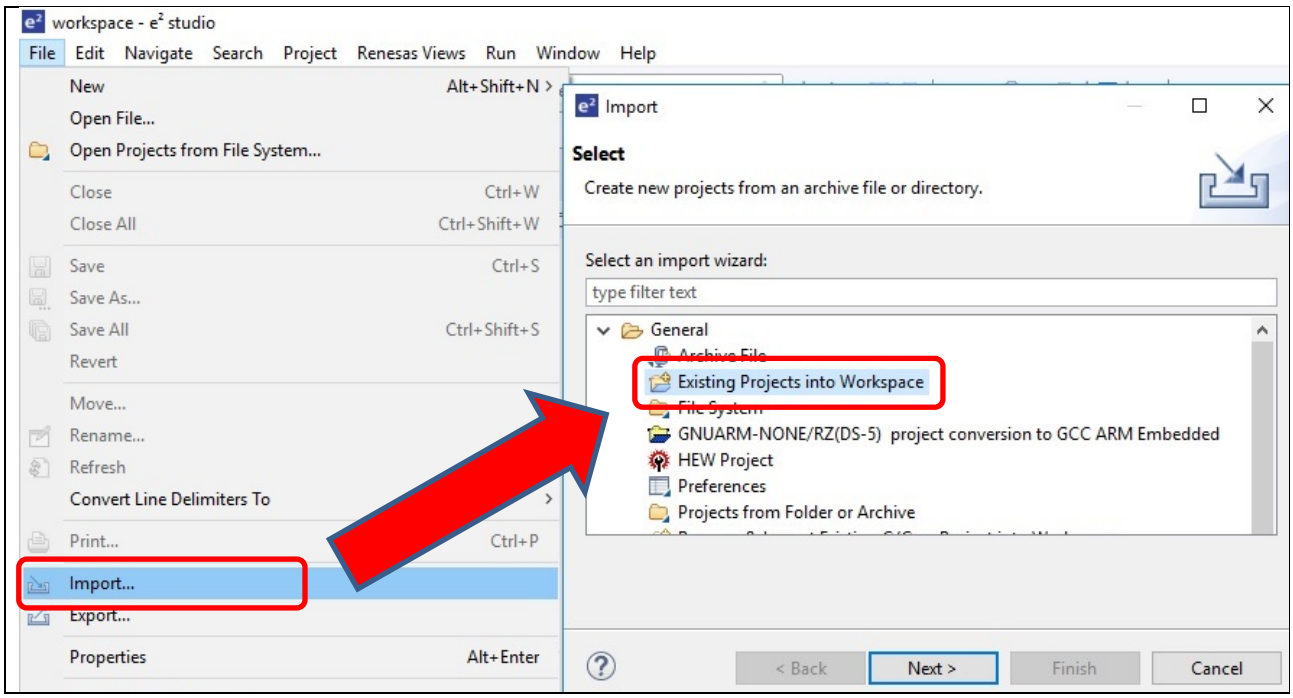

Figure 4.2 How to Open Existing e2 studio Project (Step 1)

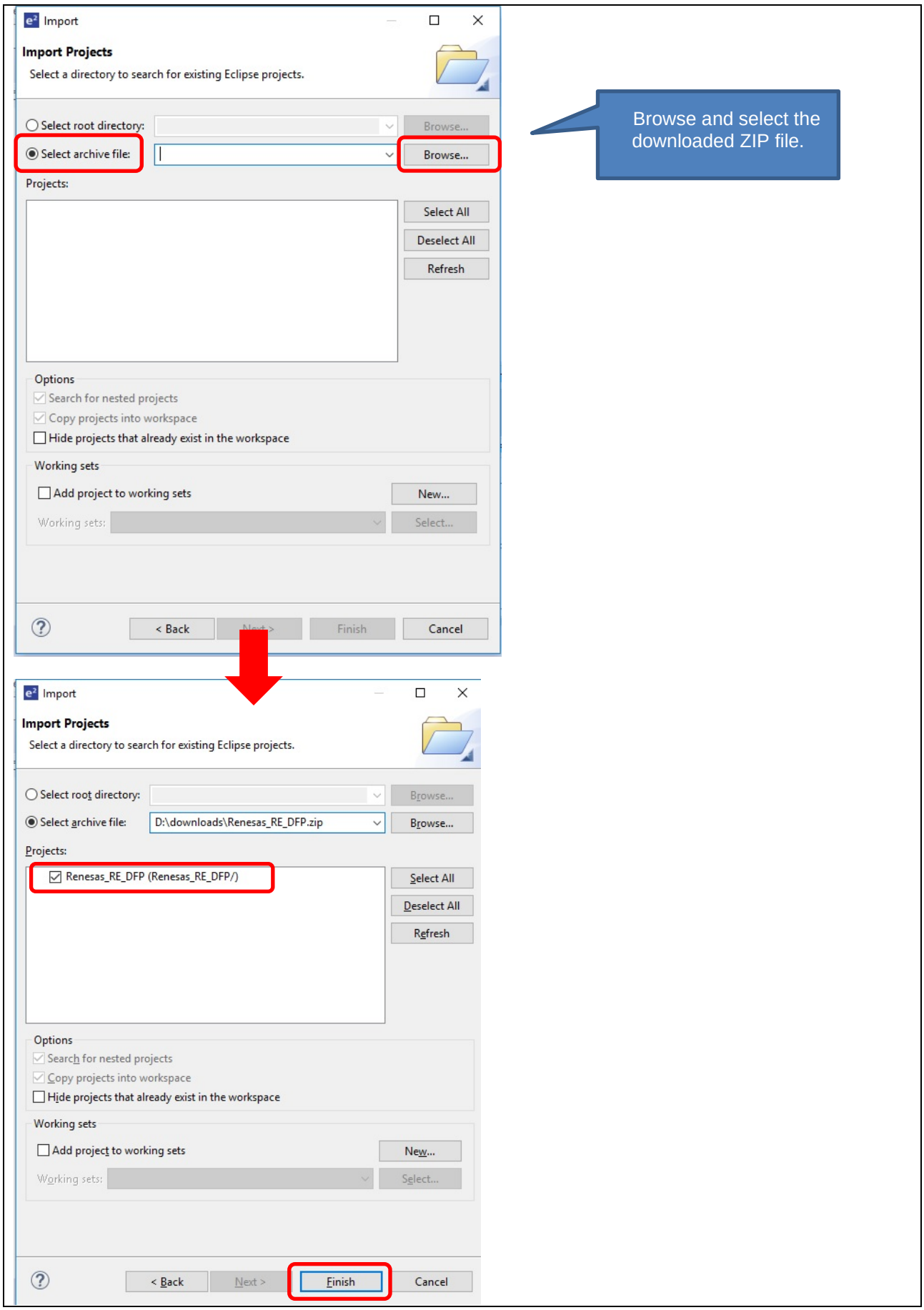

Figure 4.3 How to Open Existing e2 studio Project (Step 2)

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	2019/10/01		First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
5. Renesas Electronics products are classified according to the following two quality grades: “Standard” and “High Quality”. The intended applications for each Renesas Electronics product depends on the product’s quality grade, as indicated below.
   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

   Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user’s manual or other Renesas Electronics document.
6. When using Renesas Electronics products, refer to the latest product information (data sheets, user’s manuals, application notes, “General Notes for Handling and Using Semiconductor Devices” in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) “Renesas Electronics” as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) “Renesas Electronics product(s)” means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/.